

V_{RSM}	=	5500 V
$I_{F(AV)M}$	=	4570 A
$I_{F(RMS)}$	=	7180 A
I_{FSM}	=	$73 \cdot 10^3$ A
V_{F0}	=	0.8 V
r_F	=	0.107 m Ω

Rectifier Diode

5SDD 50N5500

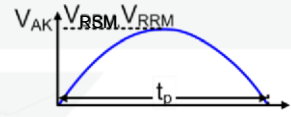
Doc. No. 5SYA1169-02 Jan. 17

- Patented free-floating silicon technology
- Low on-state and switching losses
- Optimum power handling capability

Blocking

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	Value	Unit
Max repetitive peak reverse voltage	V_{RRM}	$f = 50$ Hz, $t_p = 10$ ms, $T_{vj} = 0 \dots 150$ °C	5000	V
Max non-repetitive peak reverse voltage	V_{RSM}	$f = 5$ Hz, $t_p = 10$ ms, $T_{vj} = 0 \dots 150$ °C	5500	V



Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse leakage current	I_{RRM}	V_{RRM} , $T_{vj} = 150$ °C			400	mA

Mechanical data

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		81	90	108	kN
Acceleration	a	Device unclamped			50	m/s ²
Acceleration	a	Device clamped			100	m/s ²

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				2.8	kg
Housing thickness	H	$F_M = 90$ kN, $T_a = 25$ °C	34.5		35.2	mm
Surface creepage distance	D_s		56			mm
Air strike distance	D_a		22			mm

¹⁾ Maximum rated values indicate limits beyond which damage to the device may occur

On-state

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	$I_{F(AV)M}$	Half sine wave, $T_c = 90\text{ °C}$			4570	A
RMS on-state current	$I_{F(RMS)}$				7180	A
Peak non-repetitive surge current	I_{FSM}	$t_p = 10\text{ ms}$, $T_{vj} = 150\text{ °C}$, sine half wave, $V_R = 0\text{ V}$, after surge			$73 \cdot 10^3$	A
Limiting load integral	I^2t				$27.5 \cdot 10^6$	A ² s
Peak non-repetitive surge current	I_{FSM}	$t_p = 10\text{ ms}$, $T_{vj} = 150\text{ °C}$, sine half wave, $V_R = 0.6 \cdot V_{RRM}$, after surge				A
Limiting load integral	I^2t					A ² s

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V_F	$I_F = 5000\text{ A}$, $T_{vj} = 150\text{ °C}$		1.32	1.34	V
Threshold voltage	V_{F0}	$T_{vj} = 150\text{ °C}$ $I_F = 2500 \dots 8000\text{ A}$			0.8	V
Slope resistance	r_F				0.107	mΩ

Switching

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q_{rr}	$di_F/dt = -10\text{ A}/\mu\text{s}$, $V_R = 200\text{ V}$ $I_F = 4000\text{ A}$, $T_{vj} = 150\text{ °C}$		17500	20000	μAs
Reverse recovery current	I_{RM}			400	470	A



Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	$R_{th(j-c)}$	Double-side cooled $F_m = 81... 108 \text{ kN}$			5.7	K/kW
	$R_{th(j-c)A}$	Anode-side cooled $F_m = 81... 108 \text{ kN}$			11.4	K/kW
	$R_{th(j-c)C}$	Cathode-side cooled $F_m = 81... 108 \text{ kN}$			11.4	K/kW
Thermal resistance case to heatsink	$R_{th(c-h)}$	Double-side cooled $F_m = 81... 108 \text{ kN}$			1	K/kW
	$R_{th(c-h)}$	Single-side cooled $F_m = 81... 108 \text{ kN}$			2	K/kW

Thermal

Maximum rated values ¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T_{vj}		0		150	°C
Storage temperature range	T_{stg}		-40		150	°C

Characteristic values

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R_i (K/kW)	3.731	1.250	0.434	0.292
τ_i (s)	0.8113	0.1014	0.0089	0.0015

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

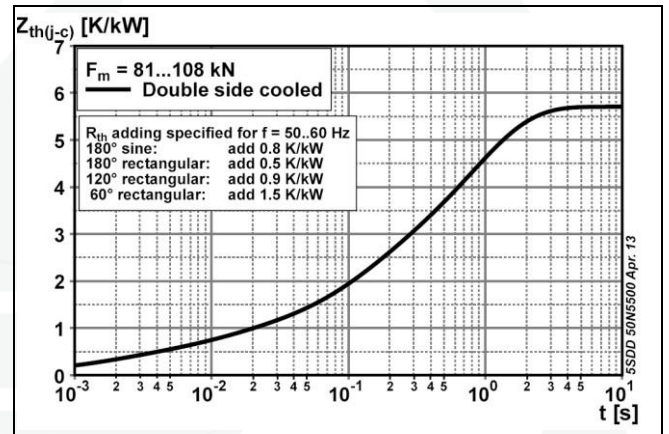


Fig. 1 Transient thermal impedance (junction-to-case) vs. time

Max. on-state characteristic model:			
$V_{F25} \approx A_{Tvj} B_{Tvj} I_F C_{Tvj} \ln(I_F + 1) D_{Tvj} \sqrt{I_F}$ Valid for $I_F = 300 - 110000 \text{ A}$			
A ₂₅	B ₂₅	C ₂₅	D ₂₅
$2.32 \cdot 10^{-6}$	$61.85 \cdot 10^{-6}$	$149.9 \cdot 10^{-3}$	$-2.67 \cdot 10^{-3}$

Max. on-state characteristic model:			
$V_{F150} \approx A_{Tvj} B_{Tvj} I_F C_{Tvj} \ln(I_F + 1) D_{Tvj} \sqrt{I_F}$ Valid for $I_F = 300 - 110000 \text{ A}$			
A ₁₅₀	B ₁₅₀	C ₁₅₀	D ₁₅₀
$-79.52 \cdot 10^{-6}$	$83.80 \cdot 10^{-6}$	$99.41 \cdot 10^{-3}$	$1.09 \cdot 10^{-3}$

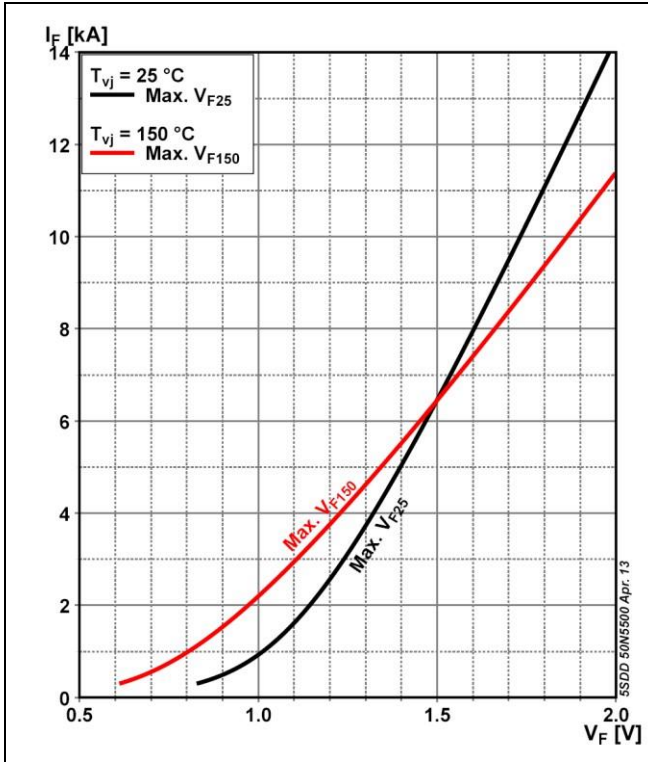


Fig. 2 On-state voltage characteristics

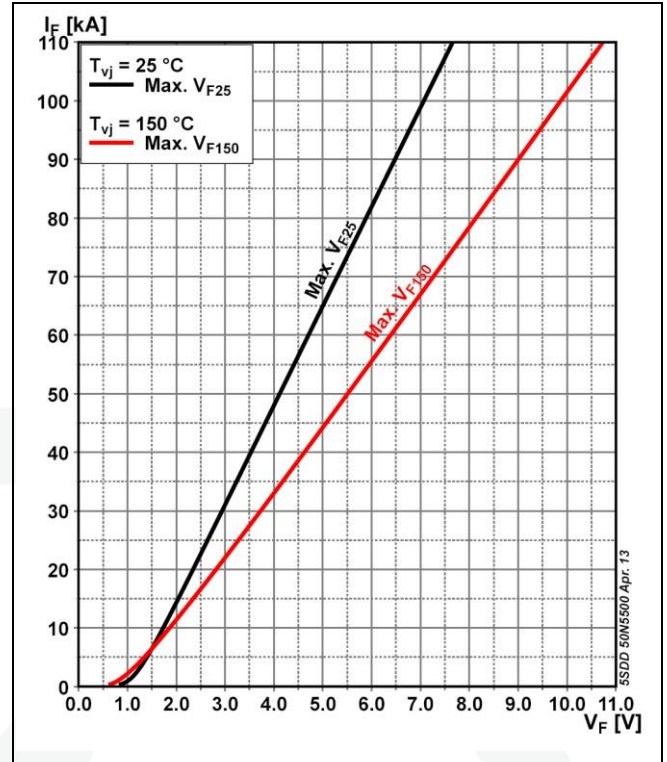


Fig. 3 On-state voltage characteristics

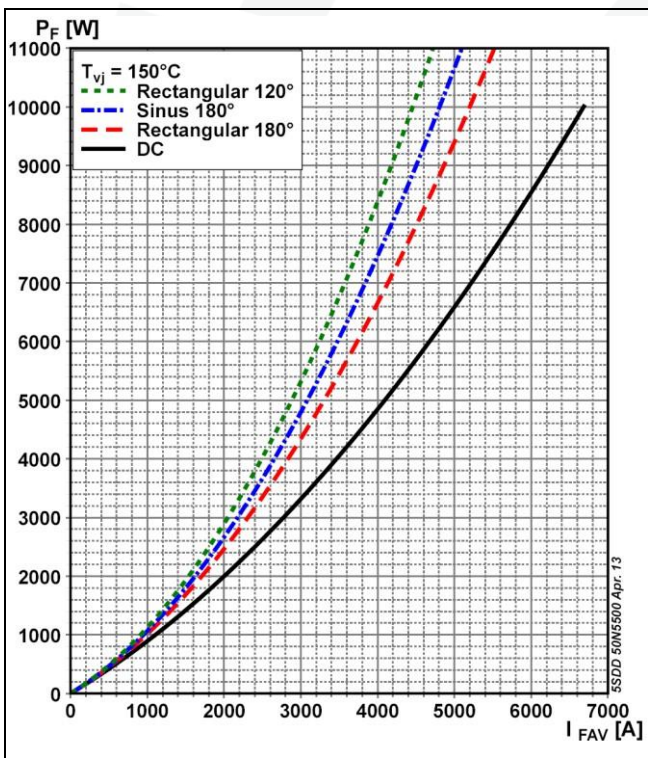


Fig. 4 On-state power dissipation vs. mean on-state current

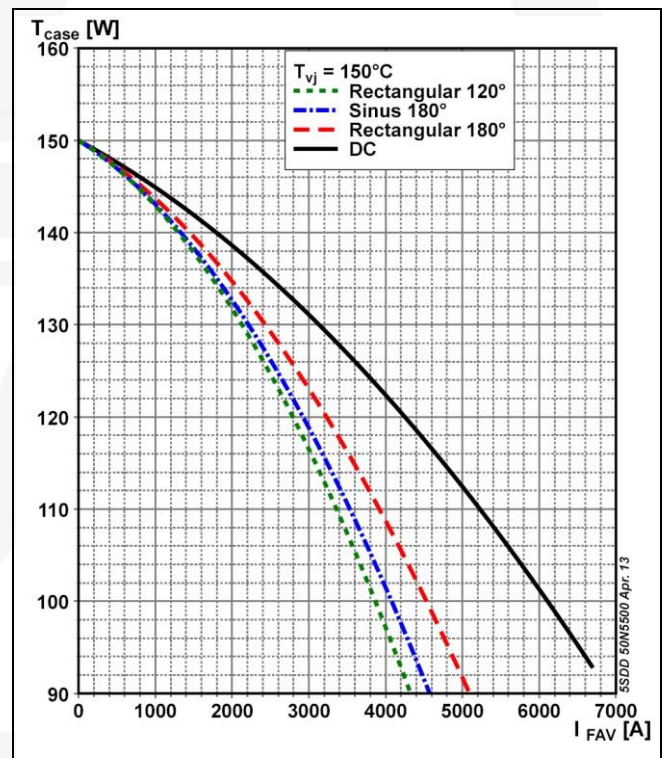


Fig. 5 Max. permissible case temperature vs. mean current

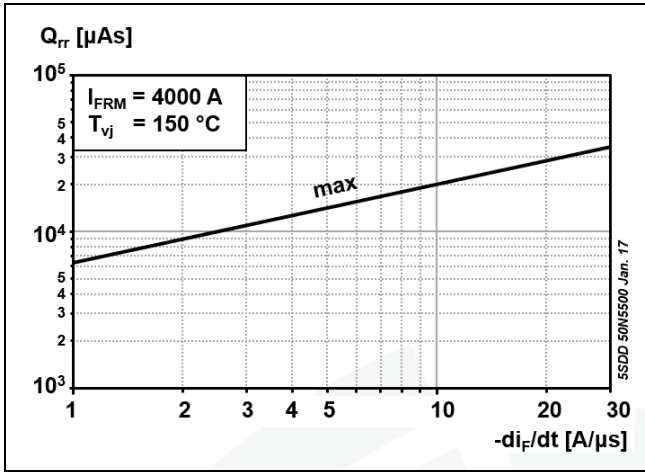


Fig. 6 Reverse recovery charge vs. decay rate of on-state current

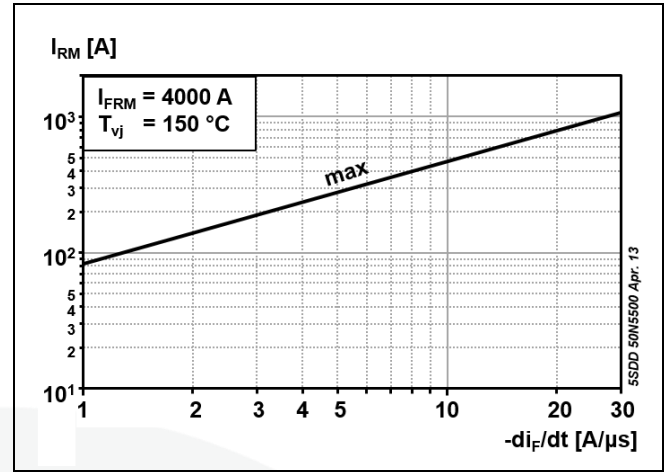


Fig. 7 Peak reverse recovery current vs. decay rate of on-state current

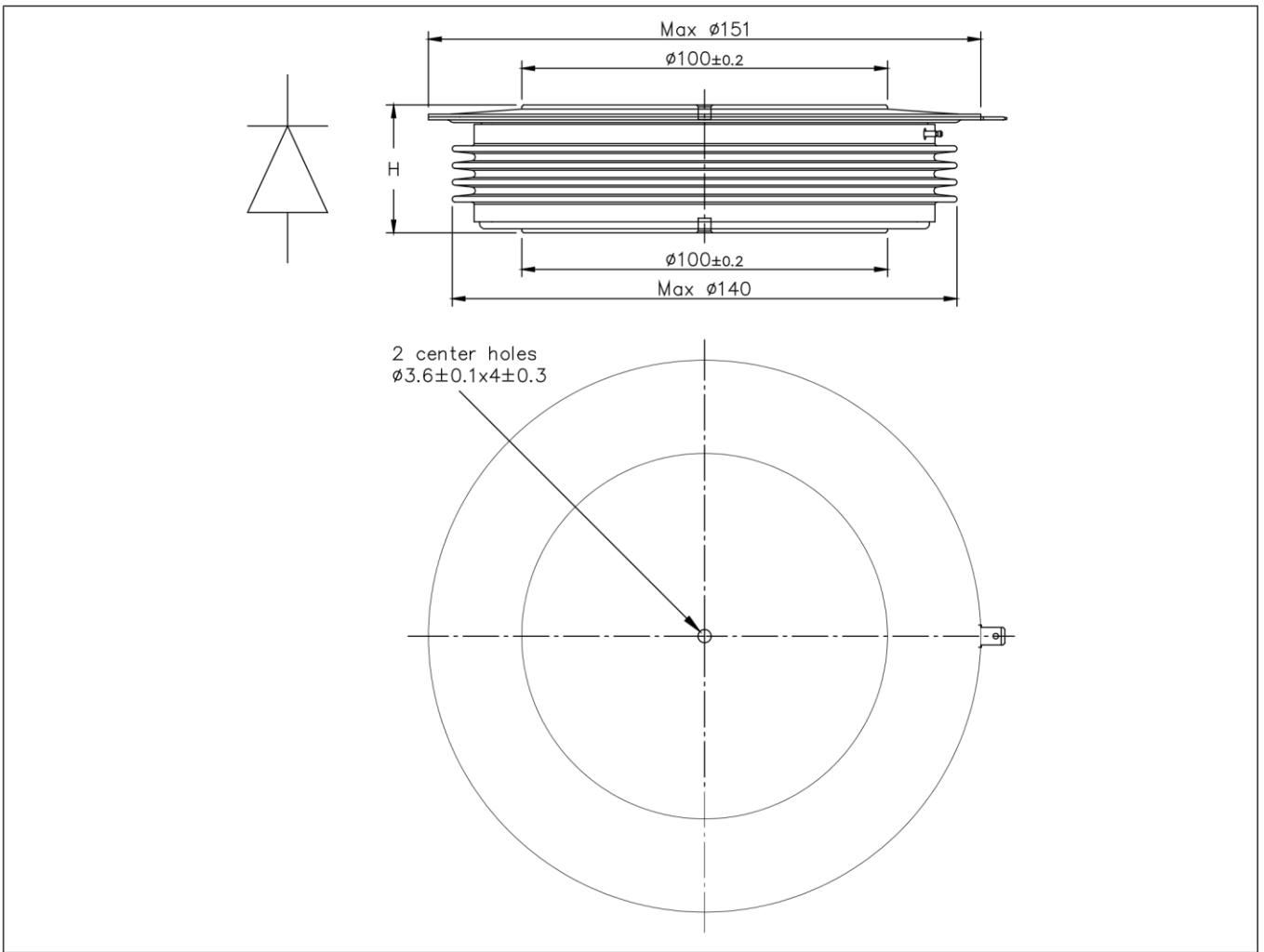


Fig. 8 Device Outline Drawing